# Upstream Tracker: the new silicon microstrip detector for the LHCb Upgrade



## **Svende Braun** on behalf of the LHCb collaboration University of Maryland

### 8th July 2022

41<sup>st</sup> International Conference on High Energy Physics (ICHEP), Bologna









## Focus on flavor physics

- $\Rightarrow$  25% of  $b\bar{b}$  production covered within 4% of solid angle.  $2 \le \eta \le 5$
- 100k b-hadrons produced every second











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- 4×10<sup>32</sup> cm<sup>-2</sup>s<sup>-1</sup>
  - high occupancy

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## Tracking upgrade



- - Provides first momenta estimate: very low pT tracks can be removed
  - ➡ Better p<sub>T</sub> resolution
  - Important reduction of 'ghost' rate from mismatched hits
- Significant speed up in reconstruction time
  - Make possible the software-only trigger

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~ Not only able to withstand 50 fb<sup>-1</sup> + 40 MHz readout, but improved performance



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## Upstream Tracker (UT)















## UT Overview

- Placed between VELO and dipole magnet
  - Long-lived particle reconstruction ( $K_s^0, \Lambda^0$ ) decaying after VELO
  - Important for upgrade triggering scheme:
    - better momentum resolution
    - Reduces 'ghost' tracks from mismatched hits









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## ~ 4 layers of silicon micro-strip detectors

→ Arranged as vertical/stereo layers (±5°) to provide x-y position of particle



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## Improved performance

- → 40 MHz readout
- **Finer granularity**: close to beam  $187.5\mu m$  pitch ->  $93.5\mu m$
- Larger coverage: closer to beampipe
- Reduced material budget



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## Silicon sensor

Sensor	Туре	Pitch	Length	Strips
А	p-in-n	187.5 µm	99.5 mm	512



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**#** sensors 888

### ∼ Top-side HV biasing

- $\sim$  Optimization with 4 designs
  - → Outer region with p-in-n, 187.5 µm pitch



Embedded pitch adapters







## Silicon sensor

Sensor	Туре	Pitch		Length	Strips
А	p-in-n	187.5	μm	99.5 mm	512
В	n-in-p	93.5	μm	99.5 mm	1024
С	n-in-p	93.5	μm	50 mm	1024
D	n-in-p	93.5	μm	50 mm	1024

### **4-ASIC module**



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**# sensors** 888 48 16 16 512 strips Туре А 1024 strips Туре В

Embedded pitch adapters

→ Inner region with n-in-p, 93.5 µm pitch

Top-side HV biasing

Cost effective

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Optimization with 4 designs

→ Outer region with p-in-n, 187.5 µm pitch

60.68 micron

0 0 0 0 0 0

Radiation-hard and good granularity -> 8-ASIC module

1024 strips Type C 1024 strips Type D

### Upstream Tracker: the new silicon microstrip tracker for the LHCb Upgrade









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Circular cutout near the beamline













- $\sim$  Extracts, shapes & digitizes analogue signals from sensors
- ~ Performs Digital Signal Processing
  - Pedestal and common mode noise subtraction
  - ➡ Zero-suppression
  - Data formatting & recorded in local on-chip memory
- Transmits serially output data
  - → Up to 5 SLVS e-links @ 320 Mbps
  - → Allows for **40 MHz readout of UT**









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- → 6-bit ADC/channel







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- →  $T_{peak} \le 25$  ns
- Short tail: < 5% after 2 T<sub>peak</sub>







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- → Input pitch 80µm
- Signal-to-Noise ratio >10







## Instrumented stave components

## ~ASICs mounted on **Hybrids**

→ 2 variants: 4-ASIC for A sensor (outer region) and 8-ASIC hybrid for B,C,D sensors in inner region













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- → Low mass flex circuit
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## Modules (hybrids & sensors) and flex Stave

- Low-mass support structure with dimensions 1.6
- Sensors overlap on front & back
- Integrated titanium pipe for CO<sub>2</sub> cooling
  - ★ Keep sensors < -5°C</p>

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- Low-mass support structure with dimensions 1.6
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- Integrated titanium pipe for CO<sub>2</sub> cooling • Keep sensors  $< -5^{\circ}C$
- → 68 staves in total
  - ◆ 16/18 staves per plane

## Instrumented stave components







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## Peripheral Electronics (PEPI)

### ~ A flexible pigtail cable connects the stave to PEPI

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### ~ Backplane distributes balanced load to Data Control Boards (DCBs) & routes power



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~ Backplane distributes balanced load to Data Control Boards (DCBs) & routes power

### ~ DCBs optically send data to LHCb DAQ via fibers

- → Bandwidth: 248 DCBs × 3 VTTx/DCB × 2 links/VTTx × 4.8 Gb/s = 7.1 Tb/s
- → Also control system via VTRx



Each **DCB** (Data Control Board) has **3 VTTx** (rad-hard optical transmitter),



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7 GBTx (rad-hard serializerdeserializer ASIC), and **1 VTRx** (optical TX/RX)













### THEP

## UT integration

### Upstream Tracker: the new silicon microstrip tracker for the LHCb Upgrade



Slide 11



### THEP

### Upstream Tracker: the new silicon microstrip tracker for the LHCb Upgrade



Slide 11









### Upstream Tracker: the new silicon microstrip tracker for the LHCb Upgrade



Slide 11



Upstream Tracker: the new silicon microstrip tracker for the LHCb Upgrade













Upstream Tracker: the new silicon microstrip tracker for the LHCb Upgrade













## Underground activities

- ~ Preparation of services in cavern before closure in beginning of April
  - → Official start of Run 3
- ~ High Voltage test with full chain completed
- ~ Cable chain preparation ongoing











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## ~ Low voltage:

- → Installation & commissioning of primary power and 220 LVRs -> remote control with fibers
- Fiber routing








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## Installation challenges

### Faced many challenges along the way:





# Installation challenges

### Faced many challenges along the way: ➡ Pigtail installation











## Installation challenges

### Faced many challenges along the way: → Pigtail installation

















## Faced many challenges along the way:

- ➡ Pigtail installation
- → PEPI cabling & commissioning



## Installation challenges









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# Installation challenges

## All C-side PEPI volumes fully installed & tested

- → DCBs, fibers, validated using bit error rate test
- ∼ Work ongoing in parallel on A- & C-side















## Faced many challenges along the way:

- Pigtail installation
- → PEPI cabling & commissioning
- → Stave installation







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## Stave installation









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## Stave installation

### 1st stave installed, March 7th









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## Stave installation



### 1st stave installed, March 7th

### 2nd stave installed, June 16th













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## Stave installation



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### 2nd stave installed, June 16th











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## Stave installation



### 2nd stave installed, June 16th











- ~ LHCb undergoing a **significant upgrade** to increase data taking rate 5×
  - ➡ Remove hardware trigger → All hits are read out
  - Increase detector longevity
  - Improve performance

### Upstream Tracker: the new silicon microstrip tracker for the LHCb Upgrade









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Upstream Tracker: the new silicon microstrip tracker for the LHCb Upgrade







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- Upstream Tracker is a key component of the upgrade trigger strategy
- Upstream Tracker is currently being installed
  - → All major components are available
  - Final stage of installation and commissioning
  - Integration into LHCb expected by end of the year

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# Thank you for your attention!

# Any questions?







### ∼ Work ongoing in parallel on A- & C-side

- ~ All major components there
  - → All **electronics** produced
  - → Stave production completed for C-side
    - ★ A-side: A-type staves need 16 Modules repaired



~ Final stage of installation and commissioning @CERN



## -> putting all components together now









### $\sim$ C-side:

Stave installation will be completed by beginning of September

→ Plan to move into cavern in September technical stop (~1 week) including mechanical installation outside of LHCb acceptance

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Lower HLT1 throughput won't be issue this year -> lower luminosity















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- → HLT1 reconstruction studies show (LHCb-FIGURE-2022-007, LHCb-FIGURE-2022-010)
  - Small impact on tracking efficiency
  - Higher ghost rate

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2022

2023







## Stave test results

- ~ Stave UTbV-9C tested at nominal conditions → CO<sub>2</sub> T=-20°C, Si bias voltage V=200V
- ~ All 14 modules tested successfully -> no issues identified
- ~ Results are in agreement with expectations & laboratory measurements
- Cooling system is working successfully









## Stave test results

- identified
- laboratory measurements











## Need for an upgrade



## Have been luminosity leveling at 4×10<sup>32</sup> **cm<sup>-2</sup>s<sup>-1</sup>** since 2011 Data sample limited to











~ Limitations for higher luminosity of 2011-2018 detector

- Overall performance degrades quickly for high occupancy
- Low efficiency for hadronic decays at higher lumi due to hardware trigger
  - High E<sub>T</sub> signatures based on CALO and MUON
- → Radiation hardness of trackers

~ Upgrade I being installed will remove these constraints

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Luminosity (1/fb) 2017 (6.5+2.51 TeV): 1.71 /fb + 0.10 /fb 2016 (6.5 TeV): 1.67 /fb 2015 (6.5 TeV): 0.33 /fb 2012 (4.0 TeV): 2.08 /fb 2011 (3.5 TeV): 1.11 /fb 2010 (3.5 TeV): 0.04 /fb Recorded Integrated 0.6 0.4 Nov Mav Jul Sep Mar

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## LHCb Run Land Run L



~ Run I: 2010-2012 data ~ Run 2: 2015-2018 data

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Broad physics program with in total  $9fb^{-1}$ of data!











SALT





## Sensor+ASIC characterization

- **Beam test** at Fermilab (March 2019)
- Type A unirradiated sensor
  - → 99.5% efficiency and SN ~ 12
- Type B sensor irradiated to 2x maximum dose
  - → 94% efficiency and SN ~ 11
    - Partly due to readout limitation, most efficiency will be recovered with LHCb readout



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Final system expected to have single-hit high efficiency (> 99%) and good signal-to-noise ratio throughout experiment lifetime

> M. Artuso et al, "First Beam Test of UT Sensors with the SALT 3.0 Readout ASIC" (2019) DOI:10.2172/1568842

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100

S/N ~ 11 94% efficienc	120 110 100 90 2 70 80 70
	60 60 50 50
←Efficiency ←Signal (Landau MPV)	30 20
Irradiated sensor (2x nomina 100 200 300 400 500 Bias Voltage (V)	<b>I)</b> 600





# Hybrid and flex cables





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ASICs mounted on hybrid flex boards

### ~ Hybrids then readout by **flex cables**

- ⇒ 3 lengths
- → 100 Ω differential input impedance traces
- → HV traces: able to withstand **up to 1000V** between adjacent lines
- → Less than 500 mV roundtrip voltage drops on power traces









- ~ Stave is readout by **Peripheral Electronics** (PEPI)
- to the whole system:







## Readout and Power Electronics







# Software-only trigger



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### LHCb upgrade trigger

### **30 MHz collision rate**

### HLT

**HLT1: full event reconstruction**, inclusive and exclusive kinematic/ geometric selections

**Buffer events to disk, online** calibration/alignment

**HLT2: offline precision PID and** track quality. Output full event information for inclusive triggers, trigger candidates, and related **PVs for exclusive triggers** 

### 100 kHz (2-5 GB/s) to storage

### ∼ Full event reconstruction (HLT1) at **30 MHz** is a **major** challenge



### **VELO+UT+forward tracking** take the bulk of time







